

Electronic Patent Application Fee Transmittal

Application Number:	10690782			
Filing Date:	21-Oct-2003			
Title of Invention:	METHOD FOR MANUFACTURING A WAFER LEVEL CHIP SCALE PACKAGE			
First Named Inventor/Applicant Name:	Jin-Hyuk Lee			
Filer:	Hosoon Lee/Stormi Davis			
Attorney Docket Number:	9903-071			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				1700